

## List of Publications by Year in descending order

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35  
papers

644  
citations

759233

12  
h-index

580821

25  
g-index

35  
all docs

35  
docs citations

35  
times ranked

701  
citing authors

#	ARTICLE	IF	CITATIONS
1	Electrodeposited Ag catalysts for the electrochemical reduction of CO <sub>2</sub> to CO. Applied Catalysis B: Environmental, 2017, 208, 35-43.	20.2	122
2	Electrodeposited IrO <sub>2</sub> /Ti electrodes as durable and cost-effective anodes in high-temperature polymer-membrane-electrolyte water electrolyzers. Applied Catalysis B: Environmental, 2018, 226, 289-294.	20.2	76
3	Factors in electrode fabrication for performance enhancement of anion exchange membrane water electrolysis. Journal of Power Sources, 2017, 347, 283-290.	7.8	54
4	An extremely low Pt loading cathode for a highly efficient proton exchange membrane water electrolyzer. Nanoscale, 2017, 9, 19045-19049.	5.6	44
5	Cu Bottom-Up Filling for Through Silicon Vias with Growing Surface Established by the Modulation of Leveler and Suppressor. Journal of the Electrochemical Society, 2013, 160, D3221-D3227.	2.9	43
6	Galvanostatic bottom-up filling of TSV-like trenches: Choline-based leveler containing two quaternary ammoniums. Electrochimica Acta, 2015, 163, 174-181.	5.2	42
7	Degradation of Bis(3-sulfopropyl) Disulfide and Its Influence on Copper Electrodeposition for Feature Filling. Journal of the Electrochemical Society, 2013, 160, D3179-D3185.	2.9	30
8	Direct fabrication of gas diffusion cathode by pulse electrodeposition for proton exchange membrane water electrolysis. Applied Surface Science, 2018, 444, 303-311.	6.1	23
9	Electrochemical Behavior of Citric Acid and Its Influence on Cu Electrodeposition for Damascene Metallization. Journal of the Electrochemical Society, 2015, 162, D354-D359.	2.9	18
10	Degradation of poly(ethylene glycol)-propylene glycol copolymer and its influences on copper electrodeposition. Journal of Electroanalytical Chemistry, 2014, 714-715, 85-91.	3.8	17
11	Electrodeposition of Cu Films with Low Resistivity and Improved Hardness Using Additive Derivatization. Journal of the Electrochemical Society, 2014, 161, D749-D755.	2.9	15
12	Decomposition of polyethylene glycol (PEG) at Cu cathode and insoluble anode during Cu electrodeposition. Electrochimica Acta, 2020, 357, 136803.	5.2	13
13	Seed Repair by Electrodeposition in Pyrophosphate Solution for Acid Cu Superfilling. Journal of the Electrochemical Society, 2013, 160, D202-D205.	2.9	12
14	Electrodeposition of Cu-Ag films in ammonia-based electrolyte. Journal of Alloys and Compounds, 2019, 775, 639-646.	5.5	12
15	Porous indium electrode with large surface area for effective electroreduction of N <sub>2</sub> O. Electrochemistry Communications, 2016, 62, 13-16.	4.7	11
16	High strength Cu foil without self-annealing prepared by 2M5S-PEG-SPS. Korean Journal of Chemical Engineering, 2019, 36, 981-987.	2.7	11
17	Observation of Bis-(3-sulfopropyl) Disulfide (SPS) Breakdown at the Cu Cathode and Insoluble Anode under Open-Circuit, Unpowered Closed-Circuit, and Electrolysis Conditions. Journal of the Electrochemical Society, 2019, 166, G61-G66.	2.9	11
18	Effects of nitrogen atoms of benzotriazole and its derivatives on the properties of electrodeposited Cu films. Thin Solid Films, 2014, 550, 421-427.	1.8	9

#	ARTICLE	IF	CITATIONS
19	Fabrication of Au Catalysts for Electrochemical Reduction of CO <sub>2</sub> to Syngas. Journal of Nanoscience and Nanotechnology, 2016, 16, 10846-10852.	0.9	9
20	Selective determination of PEG-PPG concentration in Cu plating bath with cyclic voltammetry stripping using iodide ion. Electrochimica Acta, 2020, 339, 135916.	5.2	9
21	Direct Cu Electrodeposition on Electroless Deposited NiWP Barrier Layer on SiO <sub>2</sub> Substrate for All-Wet Metallization Process. Journal of the Electrochemical Society, 2014, 161, D756-D760.	2.9	8
22	Accuracy Improvement in Cyclic Voltammetry Stripping Analysis of Thiourea Concentration in Copper Plating Baths. Journal of the Electrochemical Society, 2015, 162, H294-H300.	2.9	8
23	Real-Time Observation of Cu Electroless Deposition: Adsorption Behavior of PEG during Cu Electroless Deposition. Journal of the Electrochemical Society, 2013, 160, D3015-D3020.	2.9	7
24	Properties of nanocrystalline CuAg foil prepared via electrodeposition. Journal of Alloys and Compounds, 2021, 881, 160522.	5.5	6
25	Real-Time Observation of Cu Electroless Deposition: Synergetic Suppression Effect of 2,2'-Dipyridyl and 3-N,N-Dimethylaminodithiocarbamoyl-1-propanesulfonic Acid. Journal of the Electrochemical Society, 2014, 161, D135-D140.	2.9	5
26	The effect of inducing uniform Cu growth on formation of electroless Cu seed layer. Thin Solid Films, 2014, 564, 299-305.	1.8	5
27	Communication "Monitoring the Average Molecular Weight of Polyethylene Glycol in an Acidic Cu Plating Bath. Journal of the Electrochemical Society, 2016, 163, D747-D749.	2.9	5
28	Cyclic Voltammetry Stripping Analysis to Determine Iodide Ion Concentration in Cu Plating Bath. Journal of the Electrochemical Society, 2018, 165, H213-H218.	2.9	4
29	Influence of Reducing Agent on Chemical Decomposition of Bis(3- sulfopropyl) Disulfide (SPS) in Cu Plating Bath. Journal of the Electrochemical Society, 2021, 168, 032501.	2.9	4
30	Real-Time Observation of Cu Electroless Deposition: Effect of EDTA on Removing of Cu Oxide and Adsorption of Formaldehyde. Journal of the Electrochemical Society, 2013, 160, D3134-D3138.	2.9	3
31	In-line detection of Cu <sup>+</sup> -related species in aged Cu plating bath using flow cell-based electrochemical method. Journal of Electroanalytical Chemistry, 2021, 900, 115696.	3.8	2
32	Effects of Diffusion Layer (DL) and ORR Catalyst (MORR) on the Performance of MORR/IrO <sub>2</sub> /DL Electrodes for PEM-Type Unitized Regenerative Fuel Cells. Journal of Electrochemical Science and Technology, 2017, 8, 7-14.	2.2	2
33	Brightener breakdown at the insoluble anode by active chlorine species during Cu electrodeposition. Journal of Industrial and Engineering Chemistry, 2022, 106, 198-204.	5.8	2
34	Direct Cu Electrodeposition on Ta Using Pd Nanocolloids: Effect of Allyl Alcohol on the Formation of Seed Layer. Journal of the Electrochemical Society, 2013, 160, D3206-D3210.	2.9	1
35	Cu direct electrodeposition using step current for superfilling on Ru-Al <sub>2</sub> O <sub>3</sub> layer. Electrochimica Acta, 2014, 147, 371-379.	5.2	1